

**Features:**

- ◊ Radial leaded Devices
- ◊ Cured, flame retardant epoxy polymer insulating material meets UL94V-0
- ◊ RoHS compliant and lead-free

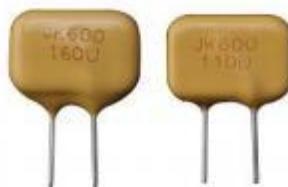
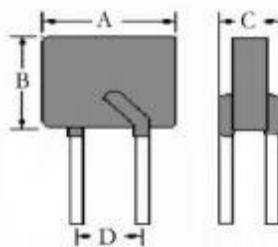
**Product Dimensions**

Fig1

JK600 Series

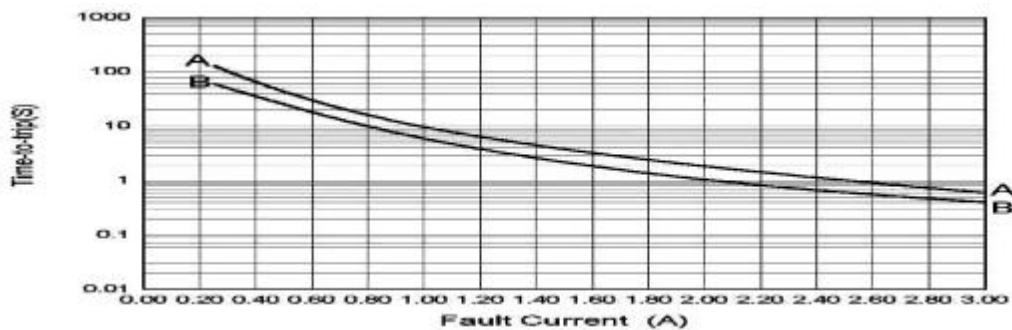
Model	Dimensions (mm)				Lead material	Shape
	A(max)	B(max)	C(max)	D(typ)	Tinned metal(mm)	Fig
JK600-110U	15	15	5.5	5.1	22AWG/Φ0.6	1
JK600-150U	15	15	5.5	5.1	22AWG/Φ0.6	1
JK600-160U	15	15	5.5	5.1	22AWG/Φ0.6	1

Note: ① Dimensions A, B, C is the maximum size, D values are typical tolerance of ± 0.75 mm.

Thermal Derating Chart-IH (A)

Model	Maximum ambient operating temperatures (°C)									
	-40°C	-20°C	0°C	25°C	30°C	40°C	50°C	60°C	70°C	85°C
JK600 series	147%	138%	119%	100%	92%	83%	73%	64%	55%	42%

Typical Time-to-trip at 25°C

Electrical Characteristic



Model	Ihold (A)	Itrip (A)	Vmax interrupt (V)	Imax (A)	Pd max (W)	Maximum Time to Trip		Resistance(Ω)
						Current (A)	Time (S)	
JK600-110U	0.11	0.22	600	3	1.0	1.0	8	6-16
JK600-150U	0.15	0.30	600	3	1.0	1.0	9	5-14
JK600-160U	0.16	0.32	600	3	1.0	1.0	10	4-12

I_H=Hold current:maximum current at which the device will not trip at 25 °C still air.

I_T=Trip current:minimum current at which the device will always trip at 25 °C still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rate

dvoltage. T_{trip}=Maximum time to trip(s) at assigned current.

P_d=Typical power dissipation:typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 °C prior to tripping.

R_{max}=Maximum device resistance at 25 °C prior to tripping.

Marking System



Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C , 1000hrs	±8% typical
Humidity aging	+85°C , 85%R.H. 1000hrs	±8% typical
Thermal shock	+125°C to -55°C , 10times	±12% typical
Resistance to solvent	MIL-STD-202 , Method 215	No change
Vibration	MIL-STD-202 , Method 201	No change

Solder reflow conditions



Wave Soldering:

Soldering Temperature:260°C~270°C

Soldering Time:≤3sec.

Soldering Position: Resettable fuse wire and the bottom ≥ 6mm.

Manual soldering:

Soldering Temperature:250°C~280°C

Soldering Time: ≤3sec.

Soldering Position: Resettable fuse wire and the bottom ≥ 6mm.

Packaging and Storage

Bag quantity

JK600-110U~JK600-160U200 Pcs/Bag

Storage

The maximum ambient temperature shall not exceed 40°C. Storage temperatures higher than 40°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning:

Please read this specification before use the product.

Using of this product must be sure to follow the requirement of this specification, operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and flame.

PPTC resettable fuses are intended for occasional over current protection. Application for repeated over current condition or prolonged trip are not anticipated.

Please avoid contact of PPTC resettable fuses with chemical solvent. Prolonged contact will damage the device performance. You are requested not to use our product deviating from the agreed specifications.